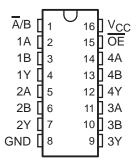
SN54HCT257, SN74HCT257 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

SCLS072D - NOVEMBER 1988 - REVISED SEPTEMBER 2003

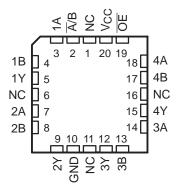
- Operating Voltage Range of 4.5 V to 5.5 V
- High-Current 3-State Outputs Interface Directly With System Bus
- Typical t_{pd} = 17 ns
- Low Power Consumption, 80-μA Max I_{CC}
- ±6-mA Output Drive at 5 V

SN54HCT257 . . . J PACKAGE SN74HCT257 . . . D OR N PACKAGE (TOP VIEW)



- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible
- Provide Bus Interface From Multiple Sources in High-Performance Systems
- Buffered Inputs and Outputs

SN54HCT257 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

The 'HCT257 devices are designed to multiplex signals from 4-bit data sources to 4-output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable (\overline{OE}) input is at the high logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	PDIP – N	Tube of 25	SN74HCT257N	SN74HCT257N		
		Tube of 40	SN74HCT257D			
-40°C to 85°C	SOIC - D	Reel of 2500	SN74HCT257DR	HCT257		
		Reel of 250	SN74HCT257DT]		
5500 1- 40500	CDIP – J	Tube of 25	SNJ54HCT257J	SNJ54HCT257J		
–55°C to 125°C	LCCC - FK	Tube of 55	SNJ54HCT257FK	SNJ54HCT257FK		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

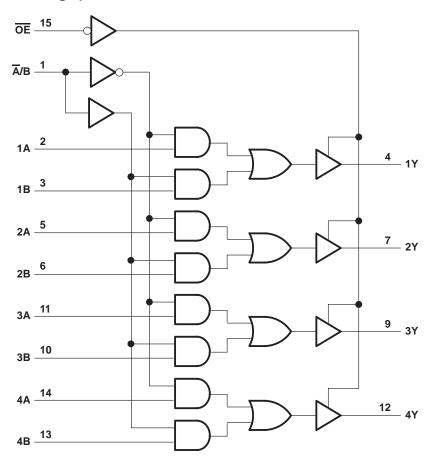


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FUNCTION TABLE

	INPU				
ŌĒ	SELECT	DA	TΑ	OUTPUT	
OE	A/B	Α	В	·	
Н	Х	Х	Х	Z	
L	L	L	X	L	
L	L	Н	X	Н	
L	Н	Χ	L	L	
L	Н	Χ	Н	Н	

logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 2): D package	
N package	
Storage temperature range, T _{Stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN	54HCT2	57	SN	74HCT2	57	LINUT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	V _{CC} = 4.5 V to 5.5 V	2	Į.	7/	2			V
VIL	Low-level input voltage	V _{CC} = 4.5 V to 5.5 V		77.	0.8			0.8	V
VI	Input voltage		0	1	VCC	0		VCC	V
VO	Output voltage		0	2	Vcc	0		VCC	V
t _t	Input transition (rise and fall) time		000	5	500			500	ns
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	7507.00	NETIONS	.,	Т	T _A = 25°C			SN54HCT257		SN74HCT257	
PARAMETER	TEST CO	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
V	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	$I_{OH} = -20 \mu A$	45.1/	4.4	4.499		4.4		4.4		
VOH	VI = VIH or VIL	$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		٧
.,	V_{OL} $V_{I} = V_{IH} \text{ or } V_{IL}$	I _{OL} = 20 μA	45.1/		0.001	0.1		0.1		0.1	V
VOL		I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4		0.33	V
lį	$V_I = V_{CC}$ or 0		5.5 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0,	$V_I = V_{IH}$ or V_{IL}	5.5 V		±0.01	±0.5	4	±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	5.5 V			8	37/	160		80	μΑ
ΔlCC [‡]	One input at 0.5 V Other inputs at 0 or		5.5 V		1.4	2.4	Oyo	3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10*		10	pF

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

[‡]This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

SN54HCT257, SN74HCT257 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

	FROM	то	,,	T	λ = 25°C	;	SN54H0	CT257	SN74H	CT257	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	4 5	V	4.5 V		20	30		45		38	
	A or B	Y	5.5 V		17	27		40		34	
^t pd	Ā/B	· ·	4.5 V		20	30		45		38	ns
	A/B	Y	5.5 V		17	27		40		34	
	ŌĒ	Υ	4.5 V		20	30	'Q'	45		38	
^t en	OE		5.5 V		17	27	(0)	40		34	ns
	ŌĒ	V	4.5 V		20	30	$g_{Q_{\zeta}}$	45		38	
^t dis	OE	Y	5.5 V		17	27) _U	40		34	ns
4.		Any	4.5 V		8	15		22		19	20
t _t		Any	5.5 V		7	14		21		17	ns

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

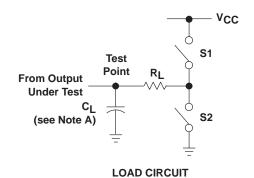
	FROM	то	.,	T,	λ = 25°C	;	SN54HCT257	SN74HCT257	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN MAX	MIN MAX	UNIT
	A D	V	4.5 V		22	38	57	48	
	A or B	Y	5.5 V		19	35	53	44	
^t pd	Ā/B	Y	4.5 V		22	38	57	48	ns
	A/B		5.5 V		19	35	53	44	
	ŌĒ	V	4.5 V		23	40	\$ 60	50	
^t en	OE	Y	5.5 V		20	38	57	48	ns
4.		Any	4.5 V		17	42	63	53	no
t _t		Any	5.5 V		14	38	57	48	ns

operating characteristics, T_A = 25°C

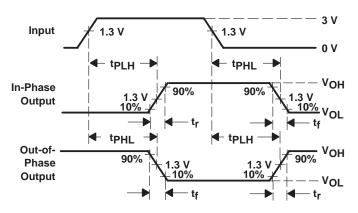
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	13	pF

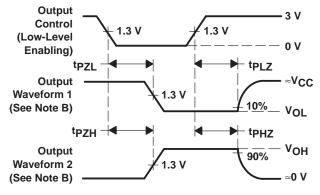
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PARAMETER MEASUREMENT INFORMATION



PARAM	PARAMETER		CL	S1	S2	
	^t PZH	1 k Ω	50 pF or	Open	Closed	
t _{en}	tPZL	1 K22	150 pF	Closed	Open	
4	tPHZ	1 k Ω	50 pF	Open	Closed	
^t dis	tPLZ	1 K22	50 pr	Closed	Open	
t _{pd} or t _t			50 pF or 150 pF	Open	Open	





VOLTAGE WAVEFORMS
OUTPUT AND 3-STATE BIDIRECTIONAL I/O
PROPAGATION DELAY TIME

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns, t_f = 6 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGE OPTION ADDENDUM





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
SN74HCT257D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257DTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HCT257N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HCT257NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

www.u.com	23-Api-2007
to Customer on an annual basis.	



TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

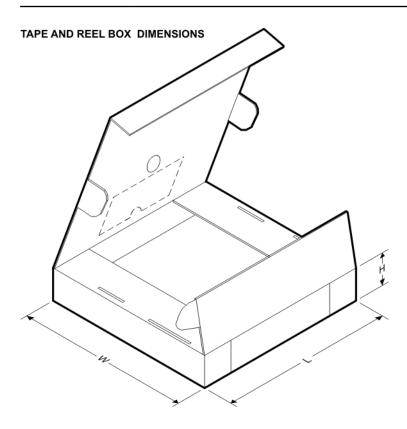
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT257DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HCT257DR	SOIC	D	16	2500	333.2	345.9	28.6

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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